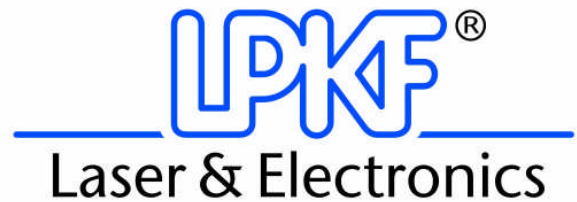


FOR IMMEDIATE RELEASE

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New Laser for Flex Circuit Processing

LPKF MicroLine UV Laser Systems

Wilsonville, OR, March 1, 2007– The new LPKF **MicroLine UV 3000** is a compact laser system designed to cut precise openings in polyimide coverlayer foils and to cut flex circuits, providing flexibility, reliability, and high precision. The **MicroLine UV 3000** reduces product changeover time, making it an efficient component to any fabrication process. This system represents the next generation in LPKF lasers by addressing critical applications in prototyping and pre-series production.

The **MicroLine UV 3000** laser cutting system raised the bar with a new high speed linear drive for flexible circuits, featuring greater positioning accuracy, higher speed, and faster acceleration; resulting in reduced processing times. The **MicroLine UV 3000** laser system is fast and encompasses versatile tools with the ability to perform precision cutting, routing, skiving, drilling, cutting pockets, structuring of etch/solder resist, micromachining of ceramic substrates, and more. Jim Greene, Vice President of Sale noted, “These capabilities noticeably reduce changeover time, making it an efficient component of any fabrication process, especially where physical space is a premium.”

With 15 years of experience in laser applications for the electronics industry, LPKF systems come with the highest standard of quality, making LPKF a leader in the industry.



www.lpkfusa.com/images/products/mluv3000.com

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